

30V N-Channel Enhancement Mode MOSFET

Voltage

30 V

Current

200 A

Features

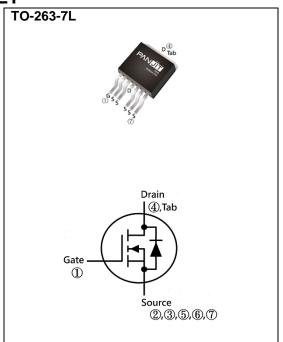
- RDS(ON), VGS@10V, ID@90A<1.4 $m\Omega$
- RDS(ON), VGS@4.5V, ID@50A<2m Ω
- Excellent FOM
- Logic Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: TO-263-7L Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 1.54 grams



Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V_{DS}	30	V	
Gate-Source Voltage		V _{GS}	±20	V	
Continuous Drain Current(Note 3)	T _C =25°C		200		
	T _C =100°C	l _D	200	Α	
Pulsed Drain Current(Note 1)	Tc=25°C	I _{DM}	700	ļ	
Power Dissipation	Tc=25°C	D-	250	W	
	T _C =100°C	Po	125		
Continuous Drain Current(Note 4)	T _A =25°C	I _D	40	^	
	T _A =70°C		33	Α	
Power Dissipation	T _A =25°C	Po	3.8	W	
	T _A =70°C		2.6		
Single Pulse Avalanche Current(Note 5)		las	28.4	Α	
Single Pulse Avalanche Energy ^(Note 5)		Eas	412	mJ	
Operating Junction and Storage Temperature Range		T _J ,T _{STG}	-55~175	°C	
Thermal Resistance ^(Note 4)	Junction to Case	R _{θJC}	0.6	°C/W	
	Junction to Ambient	$R_{\theta JA}$	40		



Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static							
Drain-Source Breakdown Voltage	BV _{DSS}	BV _{DSS} V _{GS} =0V, I _D =250uA		-	-	\ \	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.2	1.6	2.5	V	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =90A	ı	1.11	1.4		
		V _{GS} =4.5V, I _D =50A	i	1.55	2	mΩ	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V	-	-	1	uA	
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA	
Dynamic ^(Note 6)							
Total Gate Charge	Q_g	., ., ., ., .,	-	65	90	nC	
Gate-Source Charge	Q _{gs}	V _{DS} =24V, I _D =90A, V _{GS} =10V	-	8.7	-		
Gate-Drain Charge	Q_{gd}	VGS=1UV	ı	11	-		
Input Capacitance	Ciss	\\ O5\\ \\ O\\	i	4737	6200	pF	
Output Capacitance	Coss	V _{DS} =25V, V _{GS} =0V, f=1MHz	i	2131	2800		
Reverse Transfer Capacitance	Crss	I=IIVIMZ	i	78	140		
Gate resistance	Rg	f=1MHz	i	1.5	-	Ω	
Turn-On Delay Time	td _(on)	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	-	13.6	-	ns	
Turn-On Rise Time	tr	V _{DS} =24V, I _D =90A,	i	10.5	-		
Turn-Off Delay Time	td _(off)	$V_{GS}=10V, R_{G}=3\Omega$	i	46	-		
Turn-Off Fall Time	tf	(Note 2)	-	18.4	-		
Drain-Source Diode							
Diode Forward Current	Is	Tc=25°C	-	-	200	Α	
Pulsed Diode Forward Current	I _{SM}	TC=25 C	-	-	700		
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V	-	0.8	1.3	V	
Reverse Recovery Time	Trr	V _{DD} =24V,V _{GS} =0V,	ī	55	-	ns	
Reverse Recovery Charge	Qrr	Is=20A,dIs/dt=100A/us	-	56	-	nC	

NOTES:

- 1. Pulse width < 300us, Duty cycle < 2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an R_{BJC}=0.6°C/W, Package limited 200A.The chip is able to carry 240 A at 25°C.
- 4. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
- 5. Eas is calculated based on the condition of L=1mH, Ias=28.7A, V_{DD}=30V, V_{GS}=10V. 100% test at L=0.5mH, Ias=28.4A in production.
- 6. Guaranteed by design, not subject to production testing.



TYPICAL CHARACTERISTIC CURVES

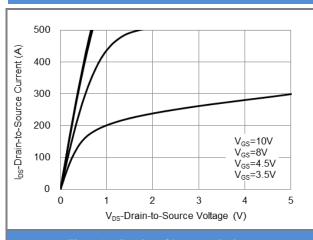


Fig.1 On-Region Characteristics

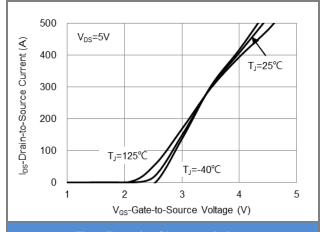


Fig.2 Transfer Characteristics

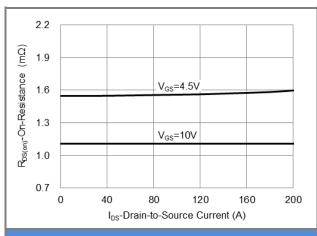


Fig.3 On-Resistance vs. Drain Current

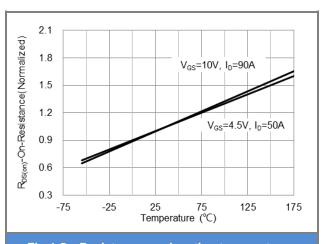
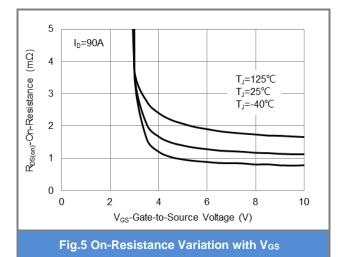


Fig.4 On-Resistance vs. Junction temperature



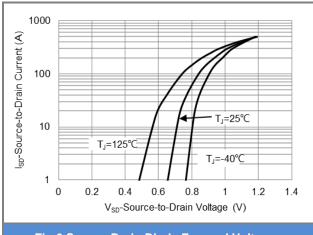


Fig.6 Source-Drain Diode Forward Voltage



TYPICAL CHARACTERISTIC CURVES

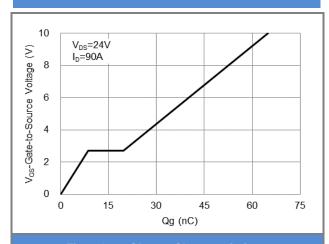


Fig.7 Gate-Charge Characteristics

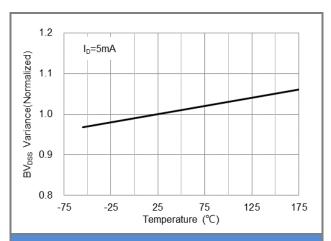


Fig.8 Breakdown Voltage Variation vs. Temperature

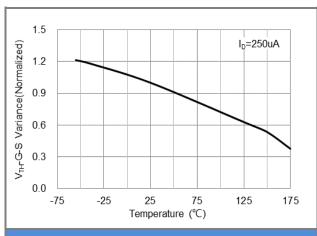


Fig.9 Threshold Voltage Variation with Temperature

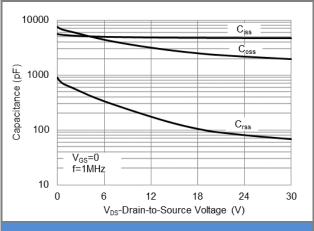
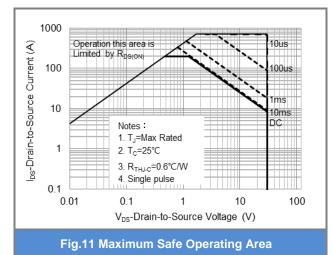


Fig.10 Capacitance vs. Drain-Source Voltage



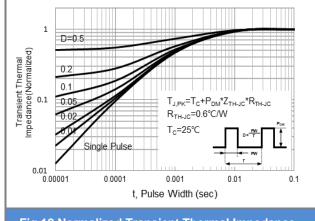


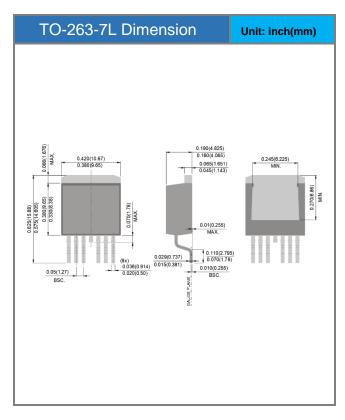
Fig.12 Normalized Transient Thermal Impedance

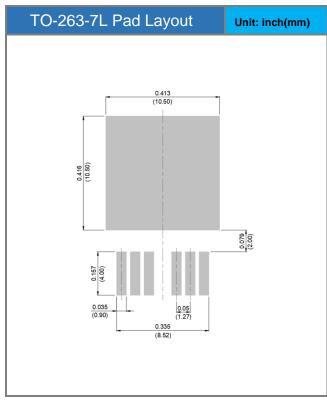


Product and Packing Information

Part No.	Package Type	Packing Type	Marking	
PJB200N03S7-AU	TO-263-7L	800 pcs / 13" reel	200N03S	

Packaging Information & Mounting Pad Layout







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